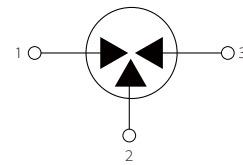


## FEATURES

- | Size Design  $\Phi 6.0 \times 8.0 \text{mm}$
- | High Current Handling Capability 10,000A @ 8/20  $\mu\text{s}$
- | Low Capacitance and Insertion Loss
- | Quick Response and Long Service Life
- | Moisture sensitivity level: Level 1
- | High Reliability and Automobile Grade(AEC-Q200)




 $\Phi 6.0 \times 8.0 \text{mm}$ 


Schematic Symbol

## APPLICATION INFORMATION

- | Communication equipment.
- | Repeaters, Modems
- | Telephone Interface, Line cards.
- | Data communication equipment.

## AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free
	UL Certificated E505857

## PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

## ELECTRICAL PARAMETER

Parameter	Symbol	Rating	Unit
DC Blocking Voltage 1)	100V/s	72-108	V
Impulse Spark-over Voltage	At 1kV/ $\mu$ s	for 99 % of measured values $\leq$ 900	V
	At 1kV/ $\mu$ s	Typical values of distribution $\leq$ 850	V
Impulse Discharge Current 2)	8/20 $\mu$ s	10	KA
Insulation Resistance	DC=50V	$\geq$ 1	G $\Omega$
Capacitance at 1MHz	V <sub>DC</sub> =0.5V	$\leq$ 2	pF
Operating and Storage Temperature		-40~125	$^{\circ}$ C

1) In ionized mode

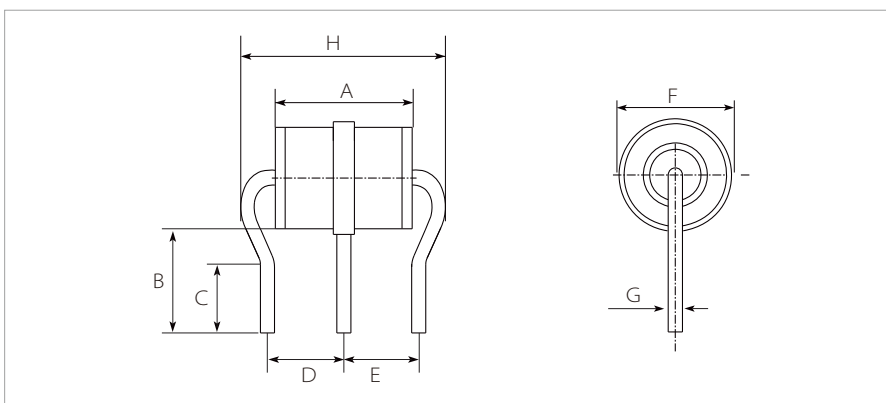
2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IIEC 61643-311

## ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85 $^{\circ}$ C ; Time:2H
Low Temperature Storage Test	Temperature: -40 $^{\circ}$ C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude: 0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260 $^{\circ}$ C; Time of dip soldering: 10s,1time

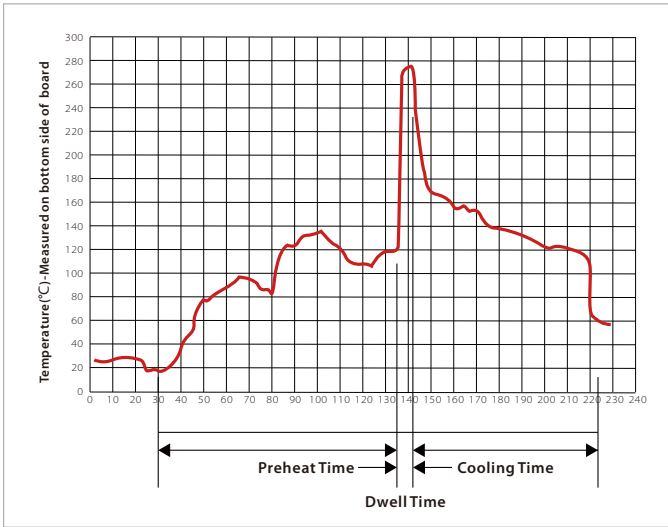
**NOTE:** Up-screen program can be specified by customer's request via contacting Semiware service

## PRODUCT DIMENSIONS



Ref.	Outline Dimensions
	Millimeters
A	8.0 $\pm$ 0.3
B	5.0 $\pm$ 1.0
C	3.3 $\pm$ 0.3
D	4.4 $\pm$ 0.3
E	4.4 $\pm$ 0.3
F	$\Phi$ 6.0 $\pm$ 0.2
G	$\Phi$ 0.8
H	11 $\pm$ 1

## WAVE SOLDERING



Wave Parameter		Lead-free assembly
Pre Heat	Temperature Min	100°C
	Temperature Max	150°C
	Time(min to max)	60 – 180 secs
Solder pot Temperature		280°C Max
Solder Dwell Time		2-5 seconds

## ORDERING INFORMATION

Part Number	Size	Marking	Qty/pcs		
			Tray	Inner Box	Carton
TPSG3R06B090	Φ6.0*8.0mm	SG3R06B090	100	500	6000

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**By QR Code**

Website



Wechat

To find your local partner within Semiware's global network: [www.semiware.com](http://www.semiware.com)

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